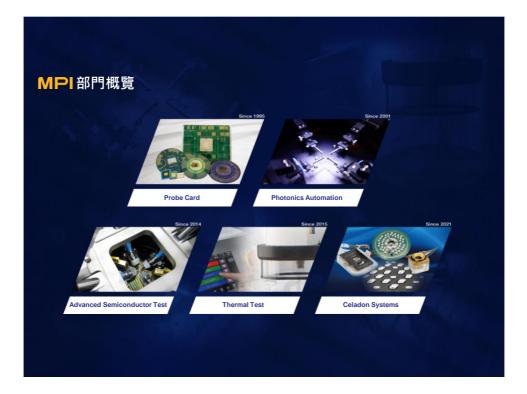


Presentation Disclaimer

The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.





供應鏈概覽





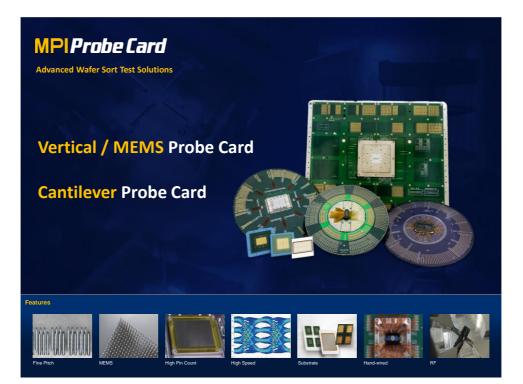


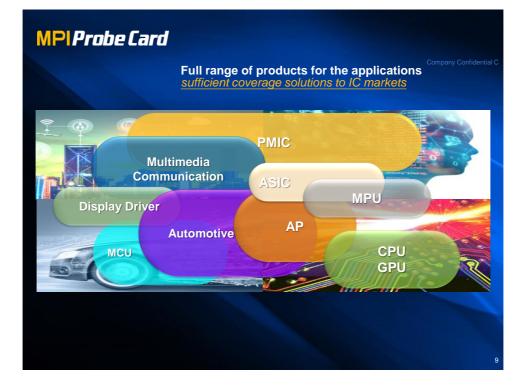
Business Contents Probe Card Photonics Automation Thermal & AST



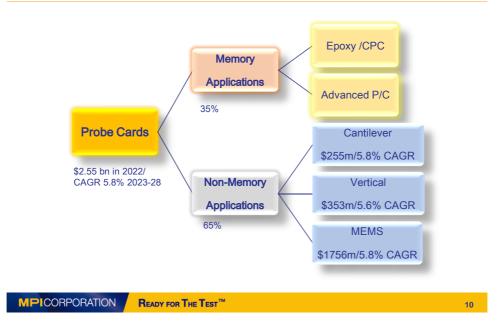
Financial Statements







全球探針卡市場概況



前十大探針卡供應商(2017-2022)

(Rank)	2017	2018	2019	2020	2021	2022
FormFactor, Inc. (USA)	1	1	1	1	1	1
Micronics Japan Co., Ltd. (Japan)	2	3	3	3	3	3
Technoprobe (Italy)	3	2	2	2	2	2
Japan Electronic Materials (Japan)	4	4	4	4	4	4
MPI Corporation (Taiwan)	5	5	5	5	5	5
SV TCL (Singapore)	6	6	6	7	8	7
Microfriend (Korea)	7	10	10	10	-	-
Korea Instrument (Korea)	8	7	8	6	7	6
Cascade Microtech (USA)	-	-	-	-	-	-
FEINMETALL (Germany)	11	12	11	14	-	-

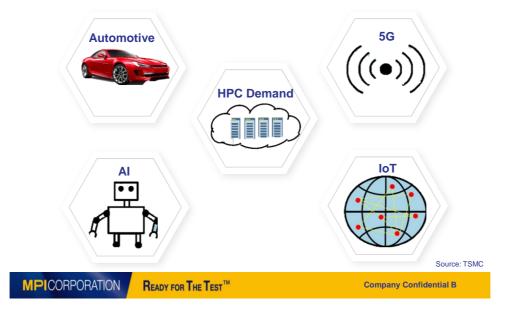
MPICORPORATION

READY FOR THE TEST[™]

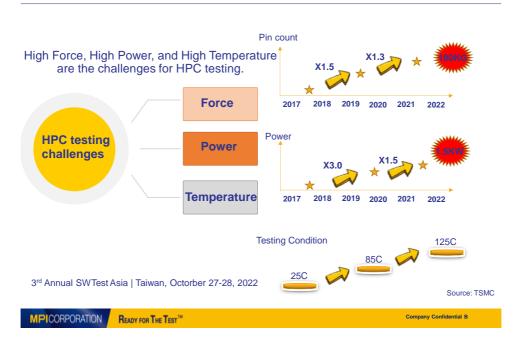
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HPC 需求

The demand of HPC (High Performance Computing) growth rapidly.



HPC 挑戰



Interface Technical Complexity Check in

Complexity Trends are on pace to be at 2022 targets(1 Cycle) or in some cases beyond

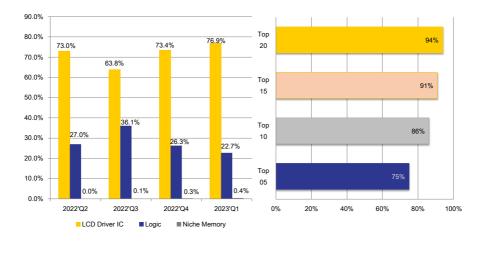
Source: VLSI Research

"2x4 Scaling"=2xPins, 2xPerformance			2018	2022	2026
	,		Level 4	Level 5	Level 6
every 4 years		Pin Pitch	90um	70um	50um
	Pin Density	Total Contact Force	80kg	150kg	250kg
<u>{₩I</u> ₩ SW Test Workshop	1/O Speed	Digital	32Gpbs	64Gpbs	128Gpbs
Semiconductor Wafer Test Workshop	I/O Speed	RF/mmWave	< 12 GHz	29 GHz	+60 GHz
2-0-1-8					
Device Interface Challenges of the		Main Power	900 mV	750mV	625mV
Next Decade	Device Power	Single Rail	35A	50A	100A
Steve Ledford	Power	Impedance	2.2 mOhm	1.4 mOhm	0.8 mOhm
TERADYNE Teradyne		Self Heating	75 W		
June 3-6,2018	Thermal	Operating Range	0 to +80C	0 to +105C	-20 to +125C
		t Expensive robe Card	\$400K*	>\$500K	>\$700K

MPICORPORATION	Ready for The Test [™]	Company Confidential B	14

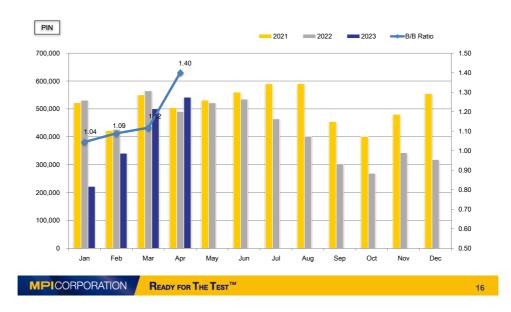
Source:Teradyne

出貨產品結構及主要客戶

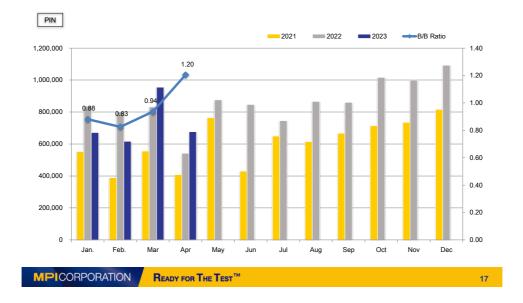


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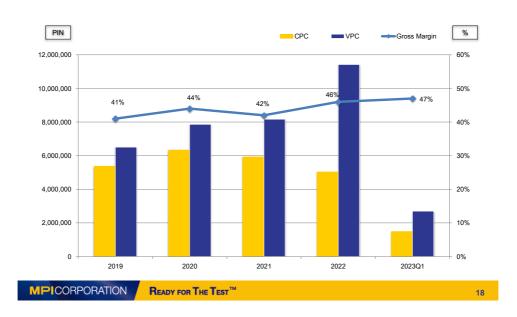
CPC月出貨針數及月接單出貨比

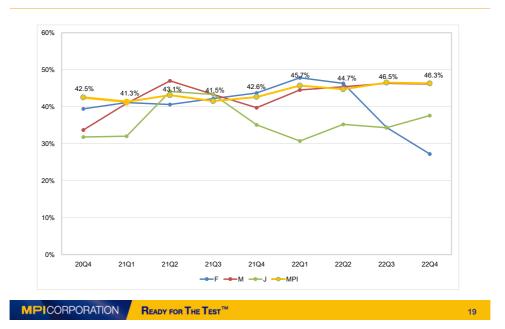


VPC月出貨針數及月接單出貨比



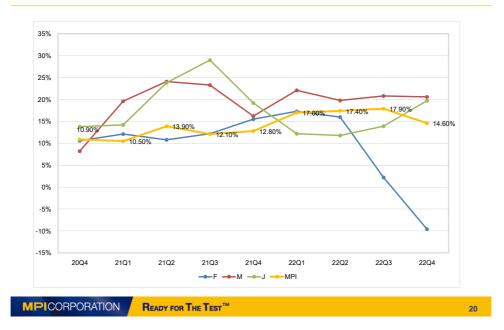
CPC及VPC成長趨勢





全球同業毛利率





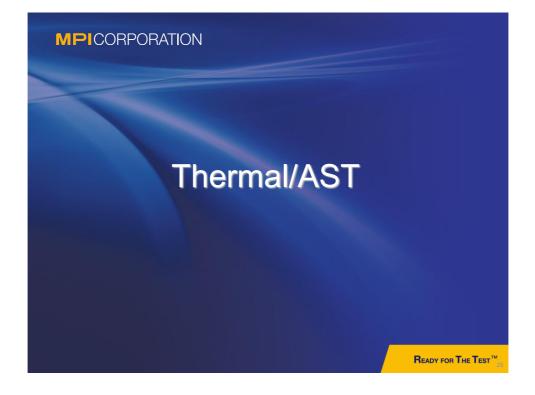




產品概覽



Company Confidential B







MPI構思

■To Combine Two Very Unique Values

The MPI Corporation

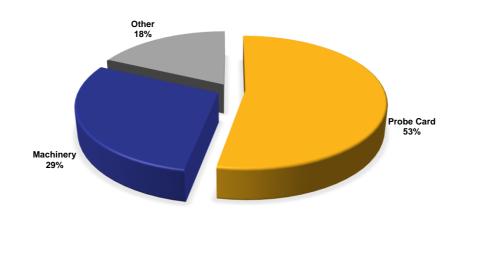
- Operational Excellence High quality, on time
 Production Test Experience 24/7 systems reliability
 Customer Centric Highest value without compromise

Management & Market Expertise

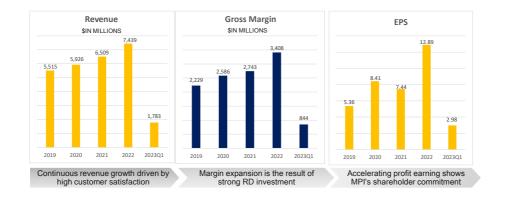
- More than 50 years together in Device Modeling, RF & mmW, WLR, High-Power, Failure Analysis, Thermal
- Visionary and Innovative Ideas
 Worldwide Partner Relationships



1Q23 出貨分布

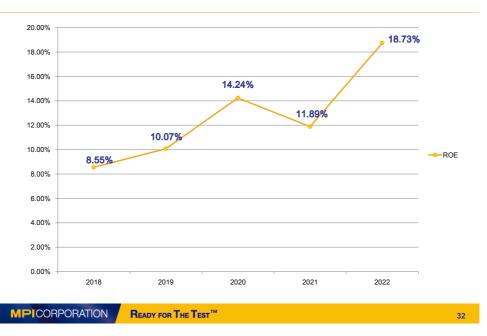


營業表現



MPICORPORATION

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股東權益報酬率

咨	斋
못	Æ

NT\$Million	2023' 1Q		2022' 1Q	
Cash and Cash Equivalents	2,385	22%	1,307	13%
Fixed Assets	4,481	41%	4,408	44%
Total Assets	10,959	100%	10,035	100%
LT Debt	996	9%	1,113	11%
Shareholders' Equity	7,204	66%	6,376	64%
EBITDA	333	18%	366	21%

*EBITDA=operating income + depreciation & amortization expenses

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NT\$Million	1Q20	23	1Q2022		
Net Sales	1,783,537	100%	1,720,155	100%	
Cost of Goods Sold	939,346	53%	934,315	54%	
Gross Profit	844,191	47%	785,840	46%	
Operating Expense	517,648	29%	492,651	29%	
Operating Income	326,543	18%	293,189	17%	
Investment Income & Others	6,864		73,674		
Net Income (before tax)	279,721	15%	306,230	18%	
EPS	2.98		3.25		

營收

